ABSTRACT

Provided is a method of manufacturing a semiconductor device, including: a step A of preparing a laminate with a plurality of electronic components mounted on a body to be mounted; a step B of preparing a thermosetting sealing sheet having an outer circumferential length of 500 mm or more; a step C of arranging the laminate on a heating plate with a surface on which the electronic components are mounted facing upward and arranging the sealing sheet on a surface of the laminate where the electronic components are mounted; and a step D of performing hot press to embed the electronic components into the sealing sheet after the step C.